



A Signal Integrity EDA Company

Optimal Corporation® Enters Into OEM Relationship with Cadence Design Systems®

PakSi®-E 3D Field Solver Quickly Extracts and Accurately Analyzes IC Package Simulation Models

SAN JOSE, Calif. – (BUSINESS WIRE) – Oct. 1, 2003 – Optimal Corporation®, a leading provider of high signal integrity simulation and analysis software serving the semiconductor IC packaging industry, today announced that it has entered into an OEM relationship with Cadence Design Systems®, Inc., (NYSE:CDN) a leader in electronic design technology and services. Under the agreement, Optimal's PakSi®-E 3D field solver technology will be integrated with the Cadence® Advanced Package Engineer (APE) product to create Cadence APE-3D. Detailed terms have not been disclosed.

"This agreement provides testimony that Optimal Corporation is a technology leader in electrical package simulation and analysis," stated Dr. An-Yu Kuo, Optimal Chief Technical Officer. "IC and package design engineers will benefit substantially from the seamless integration of the industry-leading Cadence APE product and Optimal's proven PakSi-E 3D field solver technology. We look forward to working closely with Cadence to further advance technology for the semiconductor design community."

Resulting from this relationship, Cadence's strong presence and reputation throughout the design community will provide Optimal with significantly greater access to advanced IC and package designers and application users. In return, Cadence will have access to Optimal's "best in class" 3D field solver technology, giving Cadence the opportunity to integrate Optimal's 3D field solver technology into its APE products and offer more robust, complete design, simulation and analysis solutions to its customer base.

About PakSi®-E

PakSi-E is a proven, versatile, user-friendly, fast electrical simulation and analysis tool with which engineers and designers can quickly address and resolve electrical performance issues in their advanced IC package designs with pinpoint accuracy. Embedded with the latest 3D field solver technology, PakSi-E can easily and accurately model and analyze complex power/ground structures with multiple ports and non-uniform dielectric layers in addition to traces, vias, solder bumps, bonding wires and more.

About Optimal Corporation®

Optimal is a leading provider of high signal integrity design tools. The company's breakthrough technology and engineering expertise have helped leading chip and system companies solve challenging high-speed design problems and bring industry-leading products to market. Additional information may be obtained online at <http://www.optimalcorp.com> or by e-mailing info@optimalcorp.com.

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